



# W-PROFILE ANI



(1.00 mm) .0394" PITCH • A-FSI SERIES

### **SPECIFICATIONS**

Insulator Material: Liquid Crystal Polymer Contact Material: BeCu Current Rating: 2.8 A per pin (2 pins powered) **Operating Temp Range:** 5 °C to +125 °C Plating: Au over 50 μ" (1.27 μm) Ni

#### **PROCESSING**

Lead-Free Solderable:

SMT Lead Coplanarity: (0.10 mm) .004" max (05-30) (0.15 mm) .006" max (50)\* \*(.004" stencil solution may be available; contact ipg@samtec.com) Compression Board:

Gold Pads required

## ALSO AVAILABLE MOQ Required

No alignment pin Top side alignment pin Bottom side alignment pin Other platings



## **PER ROW**

05 thru 50

(Multiples of 5)

BODY **HEIGHT** 

> -03 = 3 mm

> > -06 = 6 mm (Double Row only)

-10 = 10 mm (Double Row only)

#### **PLATING** OPTION

= 10 µ" (0.25 µm) Gold on contact, Matte Tin on tail (Not available with –03 body height)

> -S = 30 µ" (0.76 µm) Gold on contact;

> Matte Tin on tail

#### ROW **OPTION**

Single Row (Available with 5, 10 & 20 pins with -AD alignment pin)

-D = Double Row

#### **ALIGNMENT OPTION**

Leave blank for no Alignment Pin

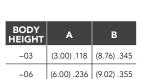
-AD = Alignment Pin Top & Bottom

#### **OTHER** OPTION

-P Plastic Pick & Place Pad (5.08 mm) .200"

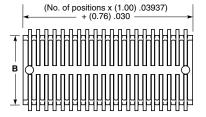
Χ (12.45 mm) .490" (Not available with -S row option or –03 body height)

-TR = Tape & Reel



(10.00) .394 (9.02) .355

-10









Double Row Version -03, -06, -10

## (No. of positions x (1.00) .03937) + (5.00).197 Applications requiring 40-50 positions without threaded





-03-AD Shown

Single Row Version -03, -06, -10

Due to technical progress, all designs, specifications and components are subject to change without notice.

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inserts, please contact Samtec Interconnect Processing Group.

Some lengths, styles and options are non-standard, non-returnable.